

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tai-Hung LIN</td> <td>06/28/2006</td> </tr> <tr> <td>Chih-Ming CHIANG</td> <td>07/06/2006</td> </tr> <tr> <td>Yi-Hsien LEE</td> <td>07/11/2006</td> </tr> <tr> <td>Chi-Ming LEE</td> <td>07/07/2006</td> </tr> </tbody> </table>		Name	Execution Date	Tai-Hung LIN	06/28/2006	Chih-Ming CHIANG	07/06/2006	Yi-Hsien LEE	07/11/2006	Chi-Ming LEE	07/07/2006
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<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	MediaTek Inc.										
<b>Street Address:</b>	No. 1-2, Innovation Road 1										
<b>Internal Address:</b>	Science-Based Industrial Park										
<b>City:</b>	Hsin-Chu City										
<b>State/Country:</b>	TAIWAN										
<b>Postal Code:</b>	300										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11474108</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11474108						
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Application Number:	11474108										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(559)432-6872										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
<b>Phone:</b>	559-432-6847										
<b>Email:</b>	info@fortneylaw.com										
<b>Correspondent Name:</b>	Andrew D. Fortney										
<b>Address Line 1:</b>	401 W FALLBROOK AVE STE 204										
<b>Address Line 4:</b>	FRESNO, CALIFORNIA 93711										
<b>ATTORNEY DOCKET NUMBER:</b>	MTKI-06-013A										
<b>NAME OF SUBMITTER:</b>	Andrew D. Fortney, Ph.D.										

OP \$40.00 11474108

Total Attachments: 2

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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

**Tai-Hung LIN**  
**Chih-Ming CHIANG**

**Yi-Hsien LEE**  
**Chi-Ming LEE**

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

**Apparatus for Testing a Chip and Methods of Making and Using the Same**

Do hereby sell, assign and transfer to MediaTek Inc., a corporation of Taiwan, R.O.C., having a place of business at No. 1-2, Innovation Road 1, Science-Based Industrial Park Hsin-Chu City, Taiwan 300, R.O.C., its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that MediaTek Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Sole/First Inventor:	
<b>Tai-Hung LIN</b>	
Inventor's Signature:	Date: Month/Day/Year
<i>Tai-Hung LIN</i>	<i>June/28/2006</i>

Full Name of Second Inventor, if any:	
<b>Chih-Ming CHIANG</b>	
Inventor's Signature:	Date: Month/Day/Year
<i>Chih-Ming Chiang</i>	<i>July/6/2006</i>

Full Name of Third Inventor, if any: <b>Yi-Hsien LEE</b>	
Inventor's Signature: <i>Yi-Hsien Lee</i>	Date: Month/Day/Year <i>Jul/11/2006</i>

Full Name of Fourth Inventor, if any: <b>Chi-Ming LEE</b>	
Inventor's Signature: <i>Chi-Ming Lee</i>	Date: Month/Day/Year <i>Jul/07/2006</i>

Full Name of Fifth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Sixth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Seventh Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Eighth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Ninth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year